DEST AVAILARIE COPY

T Missala a sa	1124	PECT AVAILABLE CUPY		
L Number	Hits 2291677		DB	Time stamp
\	2231077	or semiconductor	USPAT;	2003/05/08 09:39
		or semiconductor	US-PGPUB;	
		· .	EPO; JPO;]
	ļ	<u> </u>	DERWENT;	
2	15906	dicing	IBM_TDB	
12	13906	arcing	USPAT;	2003/05/08 09:39
	·		US-PGPUB;	1
			EPO; JPO;	
ļ		١٠.	DERWENT;	
3	7490	vacuum near3 (chuck or chucks)	IBM_TDB	
] "	1430	vacuum nears (chuck of chucks)	USPAT;	2003/05/08 09:39
			US-PGPUB;	
}		,	EPO; JPO;	
			DERWENT;	
4	20097	(wafer or wafers or substrate or substrate	IBM_TDB	2002/05/00 00 20
f -	2003,	or semiconductor) with dicing with (vacuum	USPAT;	2003/05/08.09:39
		near3 (chuck or chucks))	US-PGPUB;	ł
		nears (chack of chacks))	EPO; JPO;	
			DERWENT;	'
5	61	(wafer or wafers or substrate or substrate	IBM_TDB	2002/05/00 10 05
	"	or semiconductor) with dicing with (vacuum	USPAT;	2003/05/08 10:06
	ĺ	near3 (chuck or chucks))	US-PGPUB;	
	1	Hours (chack of chacks))	EPO; JPO;	İ
			DERWENT;	
6	20	"5809987"	IBM_TDB	2002/05/00 00.55
_			USPAT; US-PGPUB;	2003/05/08 09:55
		•	EPO; JPO; DERWENT;	
		•	IBM TDB	
7	0	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:06
		substrate or semiconductor) with dicing	US-PGPUB;	2003/03/08 10:06
	•	with (vacuum near3 (chuck or chucks))) and	EPO; JPO;	į
		farnsworth.in.	DERWENT;	1
			IBM TDB	
8	5	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:09
		substrate or semiconductor) with dicing	US-PGPUB;	2003/03/08 10:09
		with (vacuum near3 (chuck or chucks))) and	EPO; JPO;	1
		farnworth.in.	DERWENT;	
-			IBM TDB	
9	243643	blades	USPAT;	2003/05/08 10:07
			US-PGPUB;	2003,03,00 10:07
			EPO; JPO;	
			DERWENT;	
ļ	1		IBM TDB	
10	0	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:07
	ĺ	substrate or semiconductor) with dicing	US-PGPUB;	
		with (vacuum near3 (chuck or chucks)))	EPO; JPO;	
		same blades	DERWENT;	
			IBM TDB	
11	22	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:07
	İ	substrate or semiconductor) with dicing	US-PGPUB;	, 55, 55 10.07
		with (vacuum near3 (chuck or chucks))) and	EPO; JPO;	54
ļ]	blades	DERWENT;	,
	Ì		IBM TDB	
12	53	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:13
1	1	substrate or semiconductor) with dicing)	US-PGPUB;	_500,00,00 10.15
İ	l	and farnworth.in.	EPO; JPO;	
ļ	ļ	}	DERWENT;	
	i		IBM TDB	
13	402	((wafer or wafers or substrate or	USPAT;	2003/05/08 10:14
	ĺ	substrate or semiconductor) with dicing)	US-PGPUB;	2303,03,00 10.14
		and blades	. ,	
]	•	and brades	EPO: JPO: I	ı
		and brades	EPO; JPO; DERWENT;	